

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (currently amended) An electronic device comprising a plastic dual-in-line packaging (PDIP) [[package]] structure, the PDIP [[package]] structure including:
 - a lead frame including a die pad adjacent a conductive portion having at least two bends; a first plurality of leads extending from the die pad and the conductive portion and the at least two bends; a second plurality of leads separating from the die pad by a gap;
 - a die disposed on a second side of the die pad; and
 - a mold structure covering the die and the second side of the die pad, a die disposed within the mold structure; and exposing a first surface of the die pad.
 - ~~a die attach pad coupled to the die, the die attach pad having a first surface exposed from the mold structure.~~
2. (original) The electronic device of Claim 1, further comprising a motherboard, wherein the exposed first surface of the die attach is thermally coupled to the motherboard.
3. (original) The electronic device of Claim 2, wherein the exposed first surface of the die attach is in direct contact with the motherboard.
4. (currently amended) The electronic device of Claim 1, wherein the mold structure has a first surface, and [[wherein]] the exposed first surface of the die attach pad is ~~exposed from and~~ substantially flush with the first surface of the mold structure.
5. (original) The electronic device of Claim 1, further comprising a heat sink disposed in thermal communication with the exposed first surface of the die attach pad.
6. (original) The electronic device of Claim 1, further comprising a motherboard, wherein the mold structure has a first side generally facing the motherboard

and a second side opposite the first side, and wherein the first surface of the die attach is exposed from the second side of the mold structure.

7-9. (canceled)

10. (currently amended) The electronic device of Claim [[9]] 1, wherein the first plurality of [[active]] leads ~~includes a first portion of active leads~~ are located generally near a first end of the PDIP [[package]] structure and ~~a the second portion of active leads located generally near~~ a second end of the PDIP [[package]] structure, the second end of the PDIP [[package]] structure located generally opposite the first end of the PDIP [[package]] structure; and

wherein the second plurality of ~~inactive~~ leads are located generally ~~between the first and second portions of active leads.~~ in the middle of the package.

11. (currently amended) The electronic device of Claim [[9]] 1, wherein the first plurality of [[active]] leads are located generally near a first end of the PDIP [[package]], and the second plurality of ~~inactive~~ leads are located generally near a second end of the PDIP [[package]], the second end of the PDIP [[package]] structure located generally opposite the first end of the PDIP [[package]] structure.

12-21. (canceled)

22. (new) A dual-in-line package (PDIP), comprising

a die,

a lead frame including a die pad having a first surface, on which the die is attached; and a plurality of leads;

a conductive portion extending from the die pad, having at least two bends;

a first plurality of leads extending from the conductive portion and the at least two bends;

a second plurality of leads separating from the die pad by a gap and electrically coupled to the die; and

a mold structure encapsulating the die and the first surface of the die pad.

23. (new) The PDIP of claim 22, in which the mold structure has a top surface and the bottom surface.
24. (new) The PDIP of claim 23, in which the die pad has a second surface uncovered by the mold structure and is substantially flush with the bottom surface of the mold structure.
25. (new) The PDIP of claim 23, further comprising a heatsink thermally coupled to the second surface of the die pad.